

PRESS RELEASE

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WLP with optical windows

BERLINER GLAS manufactures highly-precise, structured glass wafers for the WLP of MEMS.

Encapsulation wafers with complex structures can be manufactured with a high level of precision at relatively low cost with an innovative manufacturing process. Glass wafers made of borosilicate glass in a size of up to 8" can be provided with the following features:

- Thermal coefficient of expansion adapted to the Si wafer
- A great amount of freedom for designing the cavities, even non-uniform depths
- Integration of defined, open areas (openings)
- Integration of optical windows for use with MO EMS
- Integration of metallic through-contacts (vias) for increasing the packing density (in planning)
- Tight form and position tolerances
- Very plane and parallel, low level of roughness
- Ready-to-bond (metal bond, anodic bond etc.)
- Alignment marks

BERLINER GLAS is offering an economical and industrially useful wafer-level encapsulation solution with important benefits for the customer with this product for a broad range of MEMS, RF-MEMS and MO EMS.

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